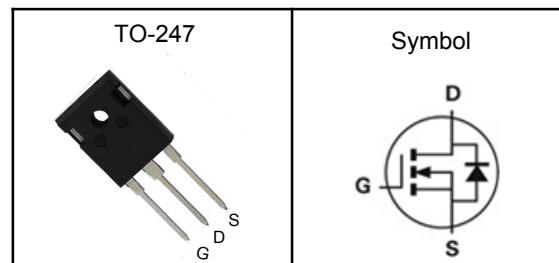


650V Super Junction Power MOSFET

Features

- Low drain-source on-resistance: $R_{DS(ON)}=0.053\Omega_{typ}$
- Very Low FOM ($R_{DS(on)} \times Q_g$)
- Extremely low switching loss
- 100% avalanche tested
- RoHS compliant

Pin Description



Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

V_{DSS}	650	V
$R_{DS(ON)-Typ}$	53	$m\Omega$
I_D	50	A

Absolute Maximum Ratings ($T_C=25^\circ C$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	650	V
V_{GSS}	Gate-Source Voltage	± 30	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
E_{AS}	Single Pulse Avalanche Energy ^③	281	mJ
$I_{DM}^{①}$	300 μ s Pulse Drain Current Tested	129	A
I_D	Continuous Drain Current	50	A
P_D	Maximum Power Dissipation	329	W
I_{AS}	Avalanche Current	6.6	A
E_{AR}	Repetitive Avalanche Energy	3.3	mJ
dv/dt	MOSFET dv/dt ruggedness, $V_{DS} = 0...400V$	50	V/ns
	Reverse diode dv/dt ^② $V_{DS}=0...400V$, $I_{SD} \leq I_D$	15	

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{θJA}^{③}$	Thermal Resistance Junction-Ambient ₁ (Max)	40	$^\circ C/W$
$R_{θJC}$	Thermal Resistance Junction-Case ₁ (Max)	0.38	$^\circ C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

650V Super Junction Power MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	650	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=600\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	2.5	---	4.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=25\text{A}$	---	53	65	$\text{m}\Omega$
R_G	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.3	---	Ω
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=50\text{V}$, Freq.=1MHz	---	3250	---	pF
C_{oss}	Output Capacitance		---	80	---	
C_{rss}	Reverse Transfer Capacitance		---	2	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=400\text{V}$, $R_G=10\Omega$, $I_D=25\text{A}$, $V_{\text{GS}}=10\text{V}$	---	17	---	nS
T_r	Turn-on Rise Time		---	8	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	70	---	
T_f	Turn-off Fall Time		---	9	---	
Q_g	Total Gate Charge	$V_{\text{DS}}=400\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=25\text{A}$	---	76	---	nC
Q_{gs}	Gate-Source Charge		---	17	---	
Q_{gd}	Gate-Drain Charge		---	34	---	
Source-Drain Characteristics ($T_J=25^\circ\text{C}$)						
$V_{\text{SD}}^{④}$	Diode Forward Voltage	$I_S=25\text{A}$, $V_{\text{GS}}=0\text{V}$	---	0.7	1.2	V
t_{rr}	Reverse Recovery Time	$V_R=400\text{V}$, $I_F=25\text{A}$, $di/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	410	---	nS
Q_{rr}	Reverse Recovery Charge		---	7	---	nC

Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

650V Super Junction Power MOSFET

Typical Characteristics

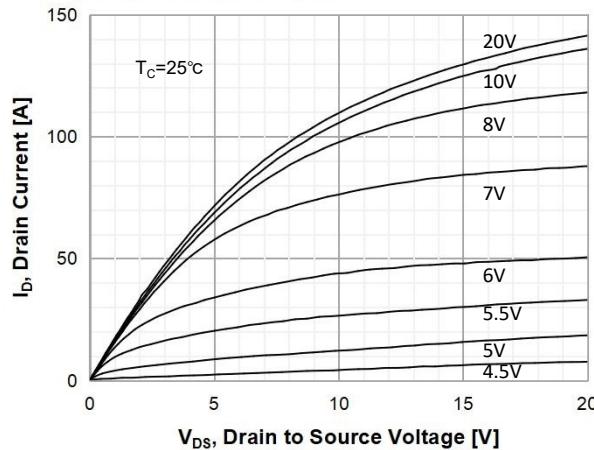


Figure 1. On-Region Characteristics

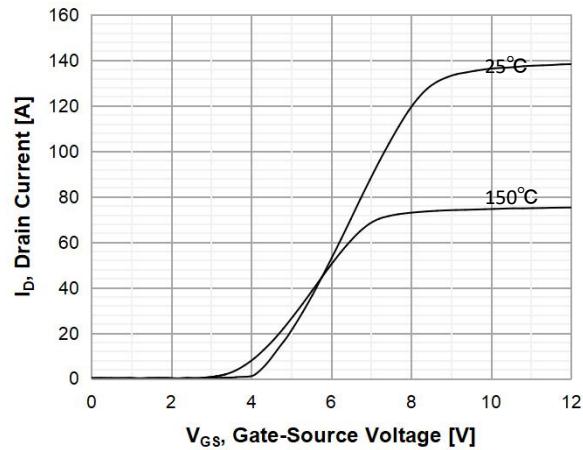


Figure 2. Transfer Characteristics

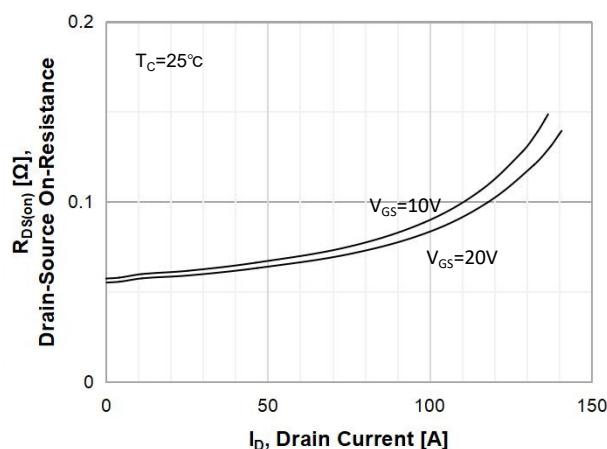


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

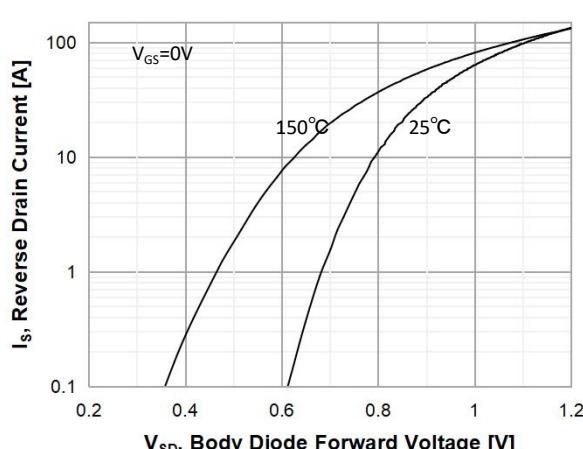


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

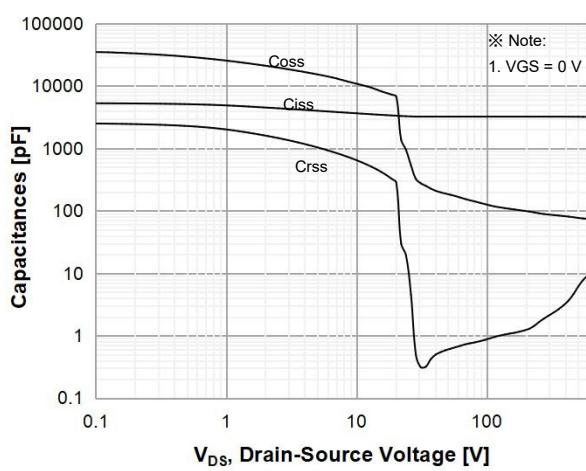


Figure 5. Capacitance Characteristics

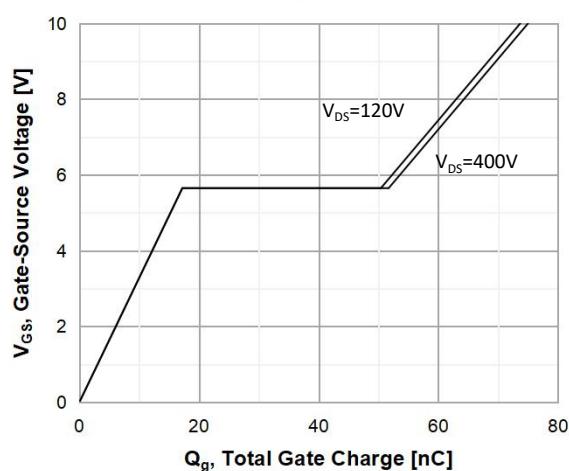


Figure 6. Gate Charge Characteristics

650V Super Junction Power MOSFET

Typical Characteristics (Continued)

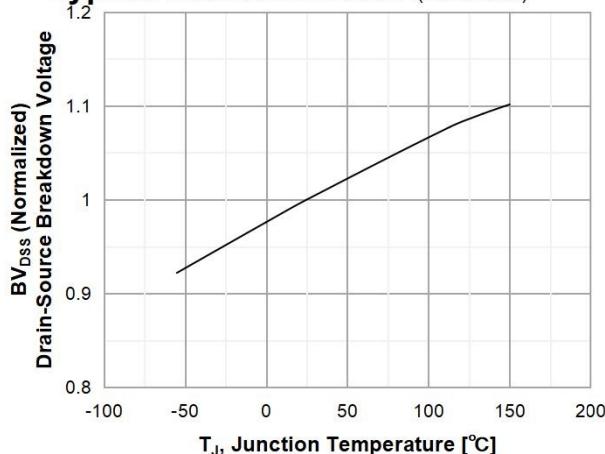


Figure 7. Breakdown Voltage Variation vs Temperature

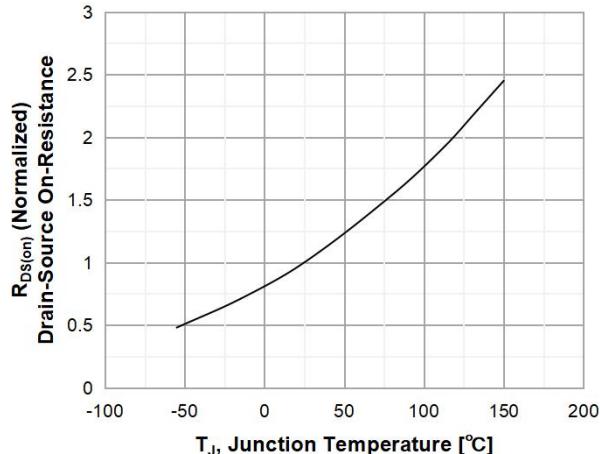


Figure 8. On-Resistance Variation vs Temperature

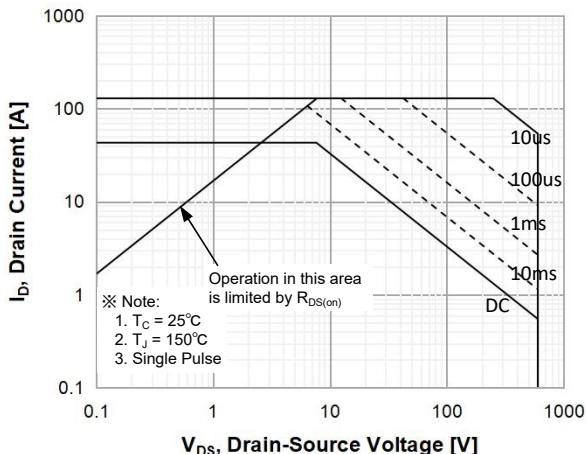


Figure 9. Maximum Safe Operating Area

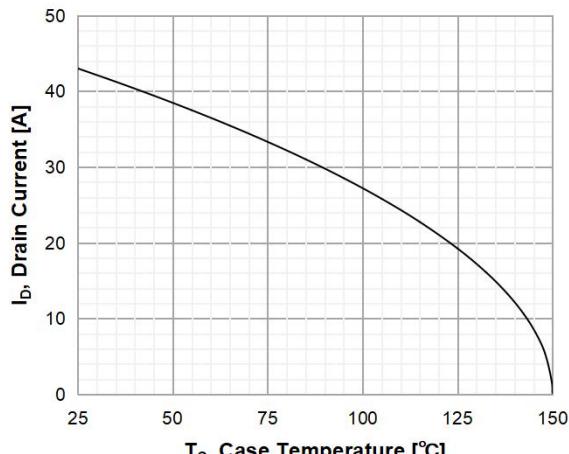


Figure 10. Maximum Drain Current vs. Case Temperature

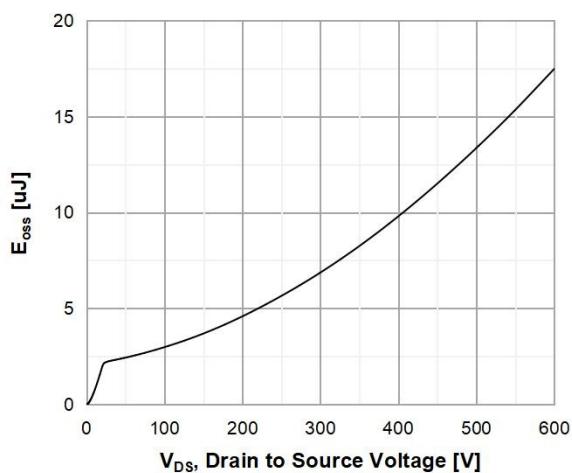


Figure 11. E_{oss} vs. Drain to Source Voltage

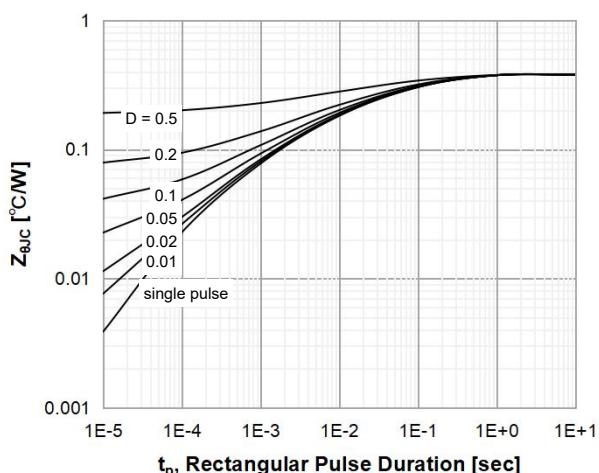
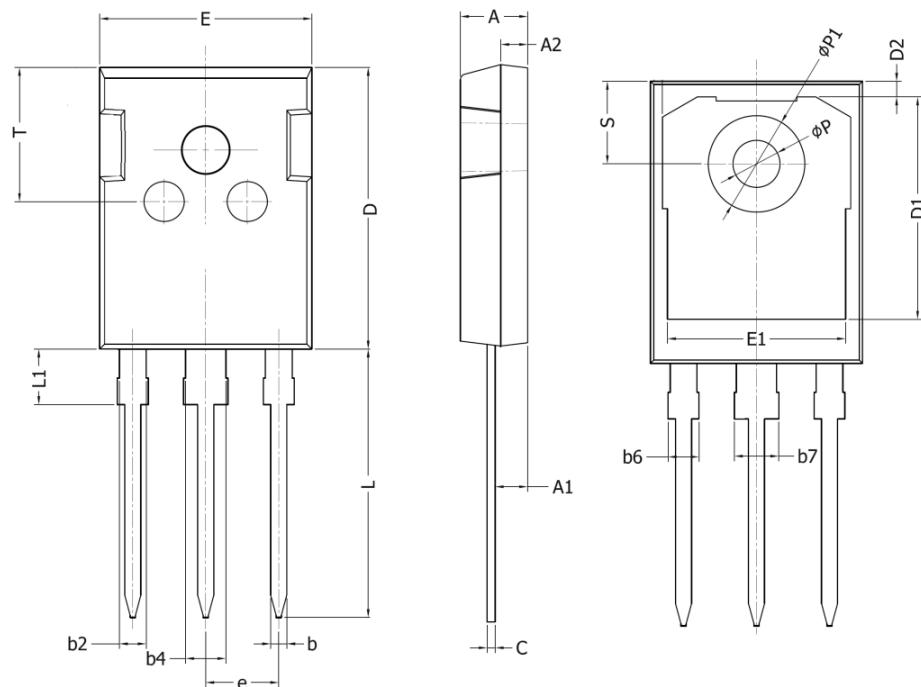


Figure 12. Transient Thermal Response Curve

650V Super Junction Power MOSFET

TO-247 Package Outline Dimensions



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.90	5.20
A1	2.31	2.51
A2	1.9	2.1
b	1.16	1.26
b2	1.96	2.06
b4	2.96	3.06
b6	-	2.25
b7	-	3.25
C	0.59	0.66
D	20.90	21.20
D1	16.25	16.85
D2	1.05	1.35
E	15.75	16.10
E1	13.00	13.60
e	5.436 BSC	
L	19.80	20.20
L1	-	4.30
P	3.40	3.60
P1	7.00	7.40
S	6.05	6.25
T	9.80	10.20